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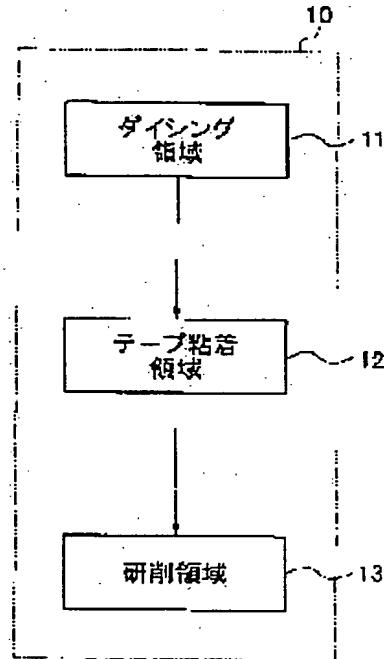
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(54) DIVIDING SYSTEM, DIVIDING METHOD AND DICING DEVICE FOR SEMICONDUCTOR WAFER

(57)Abstract:

PROBLEM TO BE SOLVED: To carry a semiconductor wafer to a grinding process without damaging it in so-called 'tip dicing', in which a dicing groove not passing through to a back surface is formed on the surface of the semiconductor wafer, then grinding the surface to divide into chips.

SOLUTION: The dividing system 10 of the semiconductor wafer is constituted of a dicing area 11, forming the dicing groove not pass through to the back surface on the street of the surface of the semiconductor wafer, a tape adhesion area 12 adhering a protective tape on the surface where the dicing groove is formed and a grinding area 13 grinding the back surface of the semiconductor wafer, until the dicing groove is exposed. In the dicing area 11, after the dicing groove is formed, the semiconductor wafer is supported from the side of the back surface by a carrying tray. In the tape adhesion region 12 or the grinding region 13, before the back surface is ground in the grinding region 13, the carrying tray is detached from the semiconductor wafer.



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